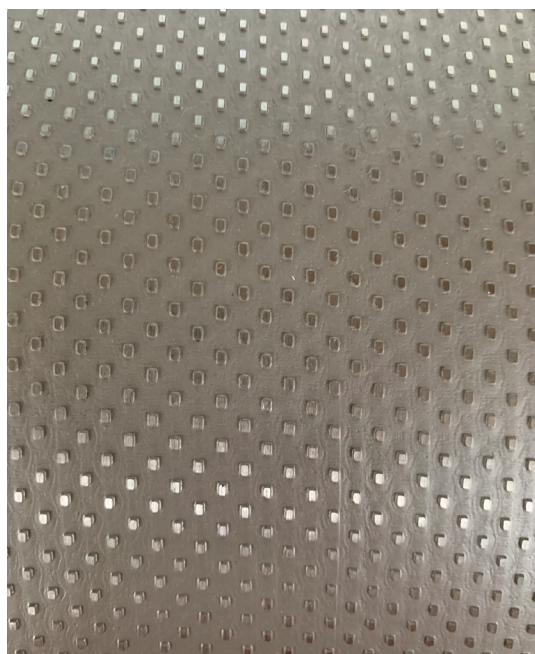


"TR" Roll Pattern

Pin spacing, center to center:	MD 5.5 mm CM 6.0 mm
Dim. of bonding area:	1.0 x 1.6 mm
Pin height:	0.6 mm
Pin area:	1.6 sqmm
Number of pins per sqcm:	5.5
Overall bonded area:	9 %
Typical applications:	Light weight composites; protective apparel, wipes.
Limitations:	The low pin height and high bond point density is making it not suitable for heavier weight composites.



Call 518-842-0073 x 615

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